

TQP4M9072

High Linearity 6-Bit, 31.5dB Digital Step Attenuator



Mechanical Information

Package Information and Dimensions

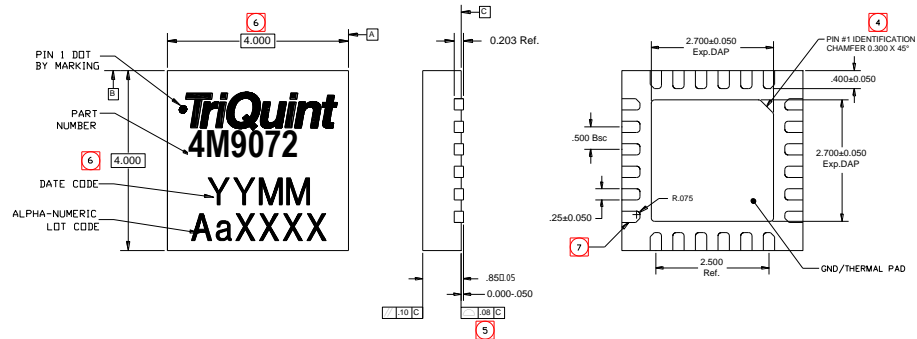
This package is lead-free, RoHS-compliant, and green. The plating material on the pins is annealed matte tin over copper. It is compatible with both lead-free (maximum 260 °C reflow temperature) and leaded (maximum 245 °C reflow temperature) soldering processes.

The component will be laser marked with "4M9072" product label with an alphanumeric lot code on the top surface of the package.

NOTES:

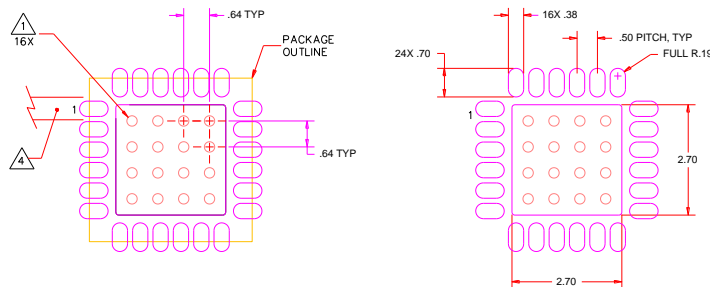
- EXCEPT WHERE NOTED, THIS PART OUTLINE CONFORMS TO JEDEC STANDARD MO-220, ISSUE E (VARIATION VGCC) FOR THERMALLY ENHANCED PLASTIC VERY THIN FINE PITCH QUAD FLAT NO LEAD PACKAGE (QFN).
- DIMENSIONING & TOLERANCING CONFORM TO ASME Y14.4M-1994.
- ALL DIMENSIONS ARE IN MILLIMETERS. ANGLES ARE IN DEGREES.

- THE TERMINAL #1 IDENTIFIER AND TERMINAL NUMBERING CONVENTION CONFORM TO JESD 95-1 SPP-012.
- COPLANARITY APPLIES TO THE EXPOSED GROUND/THERMAL PAD AS WELL AS THE TERMINALS.
- PACKAGE BODY LENGTH/WIDTH DOES NOT INCLUDE PLASTIC FLASH PROTRUSION ACROSS MOLD PARTING LINE.
- DEVIATION FROM JEDEC STANDARD MO-229, ISSUE C, 12 LEAD COUNT NOT

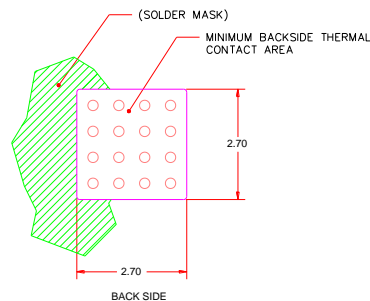


Mounting Configuration

All dimensions are in millimeters (inches). Angles are in degrees.



COMPONENT SIDE



BACK SIDE

NOTES:

- GROUND/THERMAL VIAS ARE CRITICAL FOR THE PROPER PERFORMANCE OF THIS DEVICE. VIAS SHOULD USE A .35mm (#80 / .0135") DIAMETER DRILL AND HAVE A FINAL, PLATED THRU DIAMETER OF .25mm (.010").
- ADD AS MUCH COPPER AS POSSIBLE TO INNER AND OUTER LAYERS NEAR THE PART TO ENSURE OPTIMAL THERMAL PERFORMANCE.
- TO ENSURE RELIABLE OPERATION, DEVICE GROUND PADDLE-TO-GROUND PAD SOLDER JOINT IS CRITICAL.
- RF TRACE WIDTH DEPENDS UPON THE PC BOARD MATERIAL AND CONSTRUCTION.
- USE 1 OZ. COPPER MINIMUM.
- ALL DIMENSIONS ARE IN MILLIMETERS. ANGLES ARE IN DEGREES.

Notes:

- Ground vias are critical for the proper RF performance of this device. Vias should use a .35mm (#80 / .0135") diameter drill and have a final plated thru diameter of .25 mm (.010").
- Add as much copper as possible to inner and outer layers near the part to ensure optimal thermal performance.